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2016年2月

FGA25S125P

1250 V, 25 A 阳极短路 IGBT

特性

- 高速开关
- 低饱和电压: V_{CE(sat)} = 1.8 V @ I_C = 25 A
- 高输入阻抗
- 符合 RoHS 标准

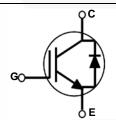
应用

• 感应加热,微波炉

概述

Fairchild 阳极短路 IGBT采用先进的场截止沟槽和阳极短路技术,可以为软开关应用提供卓越的导通和开关性能。该器件可并行配置,具有极佳的雪崩能力。该器件为感应加热和微波炉而设计。





绝对最大额定值

符号	描述	₺	FGA25S125P_SN00337	单位
V _{CES}	集电极一发射极之间电压		1250	V
V _{GES}	栅极一发射极间电压		± 25	V
I _C	集电极电流	@ T _C = 25°C	50	Α
	集电极电流	@ T _C = 100°C	25	Α
I _{CM (1)}	集电极脉冲电流		75	Α
I _F	二极管正向连续电流	@ T _C = 25°C	50	Α
'F	二极管正向连续电流	@ T _C = 100°C	25	А
P _D	最大功耗	@ T _C = 25°C	250	W
. 0	最大功耗	@ T _C = 100°C	125	W
TJ	工作结温		-55 至 +175	°C
T _{stg}	存储温度范围		-55 至 +175	°C
T _L	用于焊接的最大引脚温度, 距离	5 外壳 1/8",持续 5 秒	300	°C

热性能

符号	参数	典型值	最大值	单位
$R_{\theta JC}(IGBT)$	结至外壳热阻最大值	-	0.6	°C/W
$R_{\theta JA}$	结至环境热阻最大值	-	40	°C/W

注:

1: 受限于最大结温

封装标识与定购信息

器件标识	器件	封装	卷尺寸	带宽	数量
FGA25S125P	FGA25S125P _SN00337	TO-3PN	-	-	30

IGBT 电气特性 T_C = 25°C 除非另有说明

符号	参数	测试条件	最小值	典型值	最大值	单位
关断特性						
BV _{CES}	集电极一发射极击穿电压	V _{GE} = 0 V, I _C = 1 mA	1250	-	-	V
ΔBV _{CES} ΔΤ _J	击穿电压温度系数电压	V _{GE} = 0 V, I _C = 1 mA	-	1.2	-	V/°C
I _{CES}	集电极切断电流	V _{CE} = 1250 V, V _{GE} = 0 V	-	-	1	mA
I _{GES}	G-E 漏电流	V _{GE} = V _{GES} , V _{CE} = 0 V	-	-	±500	nA
导通特性						
V _{GE(th)}	G-E 阈值电压	I _C = 25 mA, V _{CE} = V _{GE}	4.5	6.0	7.5	V
		I _C = 25 A, V _{GE} = 15 V T _C = 25°C	-	1.8	2.35	V
V _{CE(sat)}	集电极一发射极间饱和电压	I _C = 25 A, V _{GE} = 15 V T _C = 125°C	-	2.05	-	V
		I _C = 25 A, V _{GE} = 15 V, T _C = 175°C	-	2.16	-	V
		I _F = 25 A, T _C = 25°C	-	1.7	2.4	V
V_{FM}	二极管正向电压	I _F = 25 A, T _C = 175°C	-	2.1	-	V
动态特性						
C _{ies}	输入电容		-	2150	-	pF
C _{oes}	输出电容	$V_{CE} = 30 \text{ V}, V_{GE} = 0 \text{ V},$ f = 1 MHz	-	48	-	pF
C _{res}	反向传输电容		-	36	-	pF
开关特性						
t _{d(on)}	导通延迟时间		- /	24	-	ns
t _r	上升时间		-/	250	-	ns
t _{d(off)}	关断延迟时间	V _{CC} = 600 V, I _C = 25 A,	-	502	-	ns
t _f	下降时间	$R_G = 10 \Omega, V_{GE} = 15 V,$	-	138	- /	ns
E _{on}	导通开关损耗	感性负载, T _C = 25°C	-	1085	-	uJ
E _{off}	关断开关损耗		-	580	_	uJ
E _{ts}	总开关损耗		-	1665	- //	uJ
t _{d(on)}	导通延迟时间		-	21.2	-	ns
t _r	上升时间		-	304	-	ns
t _{d(off)}	关断延迟时间	V_{CC} = 600 V, I_{C} = 25 A, R_{G} = 10 Ω , V_{GE} = 15 V, 阻性负载, T_{C} = 175°C	-	490	-	ns
t _f	下降时间		-	232	-	ns
E _{on}	导通开关损耗		-	1310	-	uJ
E _{off}	关断开关损耗		-	952	-	uJ
E _{ts}	总开关损耗		-	2262	-	uJ
Qg	总栅极电荷		-	204	-	nC
Q _{ge}	栅极一发射极间电荷	V _{CE} = 600 V, I _C = 25 A, V _{GE} = 15 V	-	15	-	nC
Q _{gc}	栅极一集电极间电荷	▼GE = 13 V	-	103	-	nC

图 1. 典型输出特性

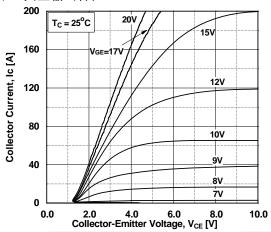


图 2. 典型输出特性

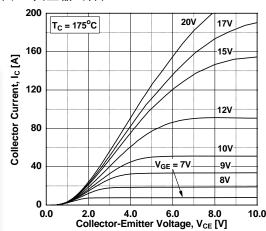


图 3. 典型饱和电压

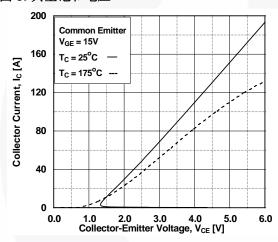


图 4. 传输特性特性

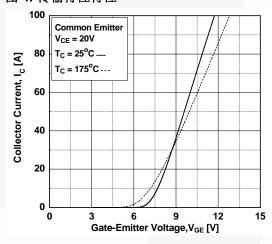


图 5. 饱和电压与可变电流强度下

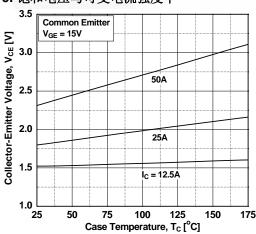


图 6. 饱和电压与 V_{GE} 的关系壳温的关系

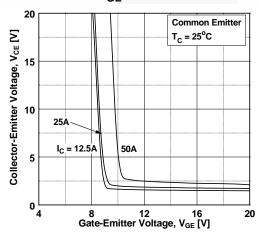


图 7. 饱和电压与 VGE 的关系

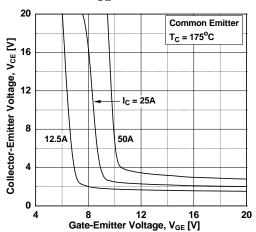


图 8. 电容特性

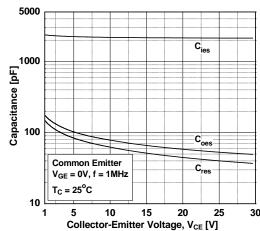


图 9. 栅极电荷特性

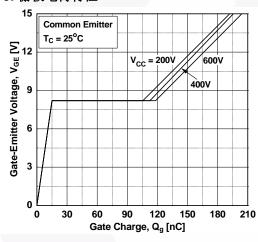


图 10. SOA 特性

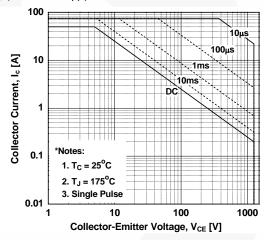


图 11. 导通特性与栅极电阻的关系

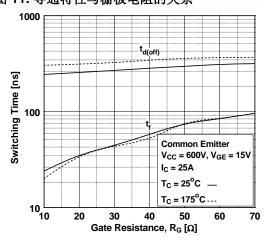


图 12. 关断特性与栅极电阻的关系

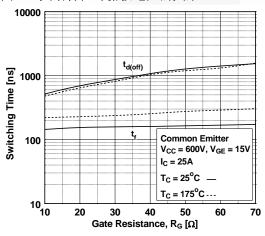


图 13. 导通特性与集电极电流的关系

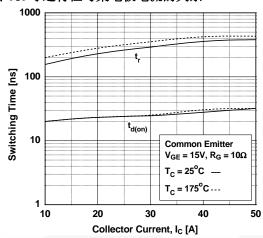


图 14. 关断特性与集电极电流的关系

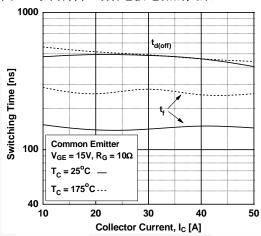


图 15. 开关损耗与栅极电阻的关系

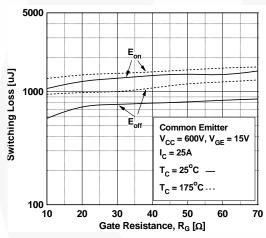


图 16. 开关损耗与集电极电流的关系

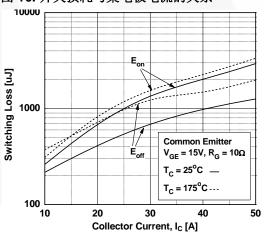


图 17. 关断开关

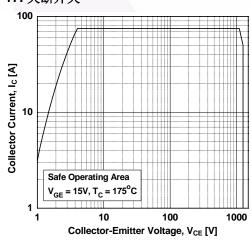


图 18. 正向特性 SOA 特性

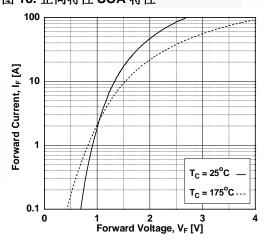
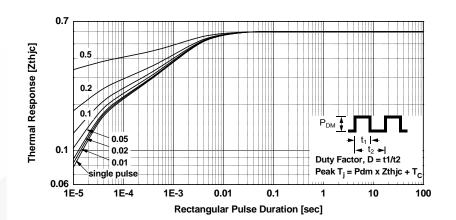
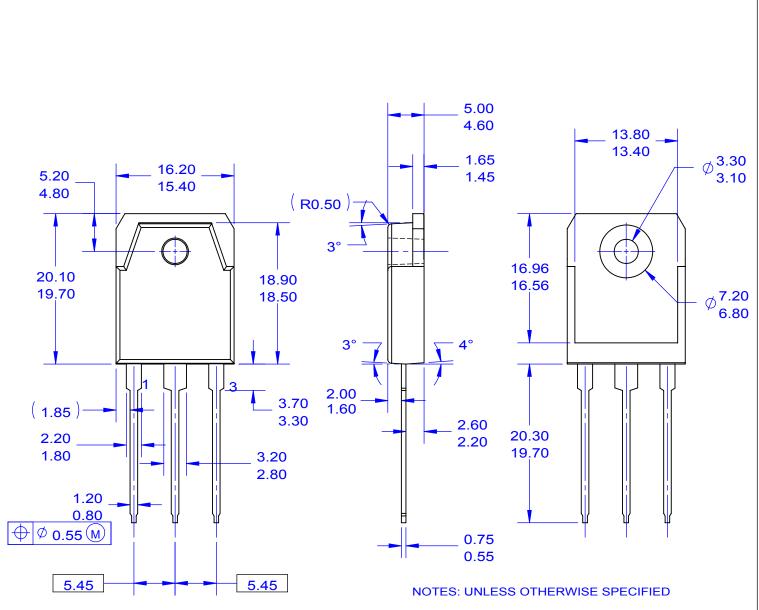
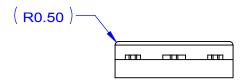


图 19. IGBT 瞬态热阻







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